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TABLE OF CONTENTS

SESSION 1: ASE FORUM

ASE Business Update & Key Technology Developments 1
Martin Tsai

Cu Wire Bonding Technology 1
Louie Huang

Advance Leadframe Package Solution: aQFN 1
Sunny Lee

Fan-out Wafer Level Package: aWLP 1
Oscar Feng

Cu Pillar Technology Status and Trend 1
Oscar Feng

Enhanced Package-on-Package Solution: aMAP PoP 1
Martin Tsai

SESSION 2A: ADVANCED PACKAGING TECHNOLOGIES (I)

Global Outlook for Embedded Device Packaging 1
Charles Bauer

Enabling MSL-1 Capability for QFN and Other Design Leadframe Packages 2
John Ganjei

Fast and Power Efficient 16X16 Array of Array Multiplier using Vedic Multiplication 6
M. S. Prahalad

Process and Characterization of Ultra-thin Film Packages 10
Tzu-Ying Kuo

Increasing Bondability and Bonding Strength of Gold Bumps Thermosonic Bonding to Flex Substrates by Depositing a Nickel Layer 14
Jong-Ning Aoh

SESSION 2B: ADVANCED PACKAGING TECHNOLOGIES (II)

Application of Self-Assembled Monolayer SAM in Low Temperature Bump-less Cu-Cu Bonding for Advanced 3D IC 18
Chuan-Seng Tan

The Contact Characteristics and NMOS Performance of ACF-Bonded Ultra-Thin Chip-on-Flex UTCOF Interconnects for Bendable Electronics 22
Yu-Ming Lin

Packaging Technologies for 3D Integration 26
Paul Collander

Electrolytic Solder Deposit for Next Generation Flip Chip Solder Bumping 30
Stephen Kenny

Development of 30 µm Pitch Cu/ni/snag Micro-bump-bonded Chip-on-chip (COC) Interconnects 34
Jing-Ye Juang

Strength Determination of Light-emitting Diodes and Chip Structure Design 38
Shin Yueh Yang

SESSION 3A: MODELING, SIMULATION, DESIGN (I)

Nanofiber Based Composites for Thermal Management 42
Johan Liu

Comprehensive Design Considerations in Die-Package-Board Transceiver Channel Co-Simulation 44
Hong Shi

Finite Element Modelling of Failures in Thick Film Chip Resistor Solder Joints 48
Chris Bailey

Delamination Fracture Characteristics for Polyimide-related Interfaces Under Fatigue Loadings 52
Tz-Cheng Chiu
Application of Numerical Analysis to the Reliability Assessment of a Novel Package on Package PoP Structure for Memory Stacking 56
Kuo-Shu Kao

SESSION 3B: MODELING, SIMULATION, DESIGN (II)

Design and Packaging of Displays for Harsh Environments .... P IC
Chris Bailey
The In-Situ Measurement of Thermal Stress on Stacked 3D-IC by Utilizing Synchrotron Radiation X-Ray 60
Heueh-Hsien Hsu
Analysis of the Heat Removal Capability of the Power Distribution Network in 3D ICs 62
Hua Ding
Compact Thermal Network Model of the Electro-Thermal System 66
Jung-Kyun Kim
The Investigation of Defect Screening Methodology using Mechanical Stress Test for Pb-free Module Product 70
Chang Graver
Unified Viscoplastic Constitutive Model for Sn3.8Ag0.7Cu Solder 74
Tz-Cheng Chiu

SESSION 4A: PACKAGING & SUBSTRATE (I)

Emerging Embedded Devices into Substrate for More than Moore Era 78
Henry Utsunomiya
In-Situ Reliability Monitoring on PBGA Packaging Through Piezoresistive Stress Sensor 82
Yu-Yao Chang
A Coreless Technology Overview for Packaging Substrates 86
Chung W. Ho
Study of UBM Consumption in Flip Chip Solder Joints under Varied Extra-High Current Density with Local Temperature Control 90
Ting-Li Yang
Processing Characteristics and Reliability of Embedded DDR2 Memory Chips 95
Yin-Po Hung

SESSION 4B: PACKAGING & SUBSTRATE (II)

Development of 20 µm Fine Pitch Microwave Contact Probe 99
Masahiro Aoyagi
Agglomeration of Ag3Sn Compounds in Microbumps during Reflow in 3D IC Packaging 103
Ruo-wei Yang
Analysis of Bump Resistance and Current Density Distribution of Ultra-Fine Pitch Microbumps 107
Yuan-wei Chang
Thermal Cycling Analysis of Microgyroscope Chip Embedded with Through-Silicon Vias by Finite Element Method 111
Chun-Lin Lu
Direct Measurement of Temperature Distribution in Flip-chip Micro-bumps Under Current Stressing Using Infrared Microscopy 115
Yu-Chun Liang
How to Find a Design Rule Which Meets Quality and Lower Cost from Micro-drill History Data 119
Angus Chung

SESSION 5: SPIL FORUM

EMI Improvement Study on Advanced Package Design 123
Robert Sung

On-Wafer Probing Measurement and Simulation Modeling Correlation of Spiral Inductors for Integrative Passive Device Application 127
Ming-Fan Tsai
Experimental and Simulation Study on NBA Structures 131
Vito Lin
The Warpage and Stress Simulation Study of Embedded Organic Substrate 135
H.S. Hsu
High Hermetic Performance of Glass Frit for MEMS Package 138
Hong-da Chang
High Thermal Dissipation and High Reliability Performance of Wafer Level High Power Light-emitting Diodes 141
Wen-Hao Lee
Three Dimensional Interconnects with Through Silicon Vias and Electroplating Solder Microbumps 145
Genie Tsai
A Study of Thin Wafer Handling in 3D-IC Applications 150
Chien-Feng Chan

SESSION 6: JAPAN PACKAGING

Bumping Technology for Flip Chip Joint and Chip & Package Interaction 153
Yutaka Tsukada
Updated R&D Result of Functionally Innovative 3D-Integrated Circuit(Dream Chip) Technology in FY2009 196
Morihiro Kada
Ultra Fine Pitch Flip Chip Interconnection for 3D Integration 198
Yasumitsu Orii
New Generation Underfills for Advanced IC Packages 222
Tatsuhiro Fujiki
Management of Thermal Interfacial Resistance for a Reparable Thermal Interface 240
Hitoshi Sakamoto

SESSION 7: ADVANCED SENSOR & MICROSYSTEMS TECHNOLOGY (MST)

Design of a High Fill-factor Micromachined Bolometer for Thermal Imaging Applications 243
Mohammed Elwan
Remote Non-contact Strain Sensor Using Carbon Nanotube-dispersed Resin 247
Yusuke Suzuki
Implementation of Accelerometer in CMOS-MEMS 251
Tsung-Chi Kuo
CMOS-MEMS Single-axis Magnetic-field Sensor for Measuring Geomagnetic Field Disturbance 254
Shih-Wei Lai
SOG Micromechanical Resonator Utilizing Single Crystal Si and CMOS ASIC 258
Li-Tao Teng
A Vibrating Micro-Resonator Design for Gyroscope Applications Using TIA 262
Sheng-Ren Chiu
Deformation and Focal Length Analysis of Electrostatic Actuated Micro Deformable Mirror 266
Meng-Ju Lin

SESSION 8: QUALITY ASSURANCE

Testing and Prevention of Head-In-Pillow 270
Ning-Cheng Lee
The Reliability Evaluation of (PTH Hole) Negative Wetting and Low Barrel Fill Phenomenon in Lead Free Process Used OSP Coated PCB by Using Thermal Cycle Testing 274
Meng-Chieh Liao
Evaluation of Board Level Reliability of Chip Scale Packages Under Thermal Cycling Test 277
Tzeng-Cherng Luo
Considerations for the Long Term Reliability of PCBs in Harsh Environmental Conditions 280
Jo Wynschenk

Evaluation of Spot Mura in TFT-LCDs using Automatic Optical Inspection 284
Fu-Ming Tzu
Accurately Simulate the Thermal Cycling Test with Improved Mechanical Reliability Test for Electronic Components 288
Yeong-shu Chen
Reliability Assessment of the PoP Lead Free Solder Joint through Temperature Cycling Test 292
Jay C.Y. Huang

SESSION 9: THEIL FORUM

DPC as a Competitor to Traditional DBC for Power and Automotive Applications 296
Heinz Ru
Direct Plated Copper Metallized Substrate for High Brightness LED Applications 324
Mike Chiu
Direct Plated Copper on Silicon for Next Generation High Power Packaging Applications 356
Victor Lin
Direct Plated Copper Substrate for RF and Microwave Packaging Applications 375
Chien-Cheng Wei
GGI Technology for the Application of Low Profile Image Sensor Module 393
C.S. Chang
Miniature Image Sensor Package 397
C.S. Chang
Thick Film Hybrid Technology for Automotive Applications 409
Brian Lu
Compression Mold Development for Multiple Propose Applications 443
Anthony Dong
Wafer Backside Coating Development for Die Attach Process 466
Klinsmenn Pan

SESSION 10: THE PERSPECTIVES OF 3D IC TECHNOLOGY

Achievement and Future Challenges in 3D Researches 486
Hirofumi Nakajima
Design, Implementation, and Test for a 3D-IC Many-Core Processor 541
Hsien-Hsin S. Lee
Advanced Solutions for 3D Integration of Heterogeneous Individual Chips 572
Gilles Poupon

SESSION 11A: THERMAL MANAGEMENT (I)

Application of Excel and Thermal Network Method to Thermal Analysis of Electronic Equipment 622
Toshio Tomimura
Design and Fabrication of Metal PCB based on the Patterned Anodizing for Improving Thermal Dissipation of LED Lighting 626
Moon-Ho Lee
Effective Thermal Management of Multiple LEDs Array 630
ChunSheng Yu
Using Thermoelectric Cooling Chip (T.E.C.) to Improve the Stability of the Heat Pipe Performance Test Instrument 634
Wei-Keng Lin
Analytical Time-Dependent Model for Satellite Thermal Balance 638
Leopoldo Ramirez
Measurement and Significance of Effective Thermal Conductivity of IMSTM Dielectric 641
Yi-Tong Shi
Thermo-mechanical Analysis of Thermoelectric Modules 645
Chun-Kai Liu

SESSION 11B: THERMAL MANAGEMENT (II)

Numerical Visualization of Heat Transfer in a Vapor Chamber 649
Yasushi Koito

Performance Tests on a Novel Vapor Chamber Using Water, Methanol or Acetone as the Working Fluid 653
Shwin-Chung Wong

Benchmark Study of Metal Core Thermal Laminates 658
Vincent Chen

An In-situ Performance Test of Liquid Cooling for a Server Computer System 662
Chien-Yuh Yang

Experimental Investigation of High Performance Thermal Module with Dimple Vortex Generators 666
Kai-Shing Yang

Vapor Chamber in High Power LEDs 670
Jung-Chang Wang

SESSION 12A: CCL MATERIALS

iNEMI HFR-Free Leadership Project Report 674
Stephen Tisdale

Advantage of Non-Etching Adhesion Promoter on High Frequency Signal Loss 681
Roger Massey

An Approach to Develop High-Tg Epoxy Resins for Halogen-Free Copper Clad Laminates 685
Ching-Hsuan Lin

The Effect of Moisture in DICY Prepreg Materials and It' s Role in Color Change of the Oxide Alternative 689
John Marshall

Influence of Reducibility of Reductant on Nickel Nanoparticles Formation on Polyimide 693
Shang-En Huang

A Low Cost Rigid-Flex Opto-electrical Link for Mobile Devices 697
Sheng-Ho Huang

DOE – QFD – SPC – FMEA..... CDT? 701
John Rankine

SESSION 12B: SOLDER & SOLDERING

Stencil Evaluation of Ultra Fine Pitch Solder Paste Printing Process 705
Vincent Lee

Formation and Growth of Intermetallics Evolution at the SAC305 and SAC0307 Solder Joints after Wave Soldering 709
Hui-Chuan Tsai

iNEMI Solder Paste Deposition Project Report 713
Cherie Chen

Warpage and Curvature Determination of PCB with DIMM Socket during Reflow Process by Strain Gage Measurement 719
Pu-Shan Huang

Role of Ni and Cu Metallization Dissolution in Various Ni/Solder/Cu Jointing Sequences 723
Chao-Sheng Liu

Preferred Crystal Orientations of Cu_6Sn_5 formed on Ni Substrate 727
Wei-Ming Chen

SESSION 13: NPC FORUM

A Study of Measurement Methodologies for the Loss Characteristics of Laminates and the Effects of Laminate Features on Loss Reduction for High Frequency Circuit Applications 730
Peter Liang

A Novel Low lose Material with Thermal Reliability for High Frequency Application 731
Gordon Lee

An Instruction to High Thermal Conductive Materials 732
Paul Huang
A Novel Highly Thermal Reliable Halogen-free System for Copper Clad Laminates 736
Mei-Ling Chen
The Double Side Shiny Copper Foil for Lithium Secondary Batteries 737
C. L. Chen
The Development and Application of Ultra Thin Copper Foil 738
Y. M. Lin

SESSION 14: ADVANCED MATERIALS, PROCESS & ASSEMBLY

Development of Electrohydrodynamic (EHD) Jet Technology 739
Han Seo Ko
Fabrication and Characterization of All-Polymer Pressure Sensors Integrated with Transduction Modules Based on Conducting Polymers 743
Pen-Cheng Wang
Pure Palladium in ENEPIG Surface Finishes – Physical Properties of the Pd Deposition and Their Influence on Soldering and Wire Bonding 747
Bill Kao
The Stress-strain Relationship of Sn63Pb37and SAC305 Solder Materials at Elevated Temperature Condition 751
Syh-Tsang Jenq
Electrochemical Corrosion and Oxidation Behaviors of High Temperature Pb-free Solders 755
Jenn-Ming Song
Effect of Underfills on Board Level Reliability of Area Array Package with Stress Calculation 759
Simon Chang
Thermal Aging Effect on Copper Wire and Micro Interfacial Frictional Behavior along Cu FAB and Al Pad 763
Hsiang-Chen Hsu

SESSION 15: PROCESS & QUALITY

Coin Insertion Technology for PCB Thermal Solution 767
Chien-Cheng Lee
Cross-Interaction between Ni and Cu across a High-Lead Solder Joint with Different Solder Volume 771
Chih-Chiang Chang
Temperature Effects on Electromigration Behavior of Solder Joints 775
Jia-Hong Ke
Ni/Cr Alloy Stripper for Flexible Wiring Boards 779
Kesheng Feng
Influence of Surface Morphology on the Adhesion Strength of Plated Cu on the Build-up Layer Within an Embedded Active Package 783
Yu-wei Huang

SESSION 16: PLATING & TREATMENT

A Novel Solvent Swell System with Enhanced Performance on Versatile Laminate Materials 787
Michael Tang
Copper Electroplating for HDI and IC Substrate Through Hole Fill 791
Mark Lefebvre
Thermal Conductivity of Bi-Te and Sb-Te Films Deposited by an Electrodeposition Process 795
Heng-Chieh Chien
Failure Analysis of ENIG Surface Finish Pad 799
Mike Huang
Oxidation behavior of ENIG and ENEPIG Surface Finish 803
Cheng-Chieh Li
The Study of The Interfacial Reaction Between Sn/Ni/Cu Substrates of PTH Components and Sn-xAg-xCu Solder Pastes after Performing Wave-soldering Process 807
Chieng-Hong Lee

Investigation of Sn Whisker Growth in the Matte Sn/Alloy 42 Substrate Coated Different Metallic Layers 811
Meng-Yu Tsou

SESSION 17: EMERGING SYSTEMS PACKAGING TECHNOLOGIES

Chip Embedding Technology for Power Applications 815
Andreas Ostmann
Stress-Induced Migration of Electroplated Copper Thin Films Used for 3D Integration 816
Naoki Saito
On 3-D IC Design for Test 820
Karl Cheng
Highly-selective MOCA Lowpass Filter Designs Using Glass-Based TF-IPD Technology 824
Tsaitzu Lee
Novel Integrated Ground Resonators for Slot-crossing Differential Line to Reduce GHz Common-mode Radiation in Advanced PCB 828
Hao-Hsiang Chuang
Reliability Assessment of the 20 um Pitch Micro-joints within a 3DIC Assembly Under Various Environments 832
Shin-Yi Huang
Warpage Simulations with P-V-T-C Equation and Experiments of Fan-out Wafer Level Package after Encapsulation Process 836
Shang-Shiuan Deng
Thermal Stresses and Deformations of Cu Pillar Flip Chip BGA Package: Analyses and Measurements 840
Jia-Ren Jhou

SESSION 18: MODELING, SIMULATION, DESIGN (III)

Nondestructive Inspection of Through Silicon Via Depth Using Scanning Acoustic Microscopy 844
Shi-Wei Lee
Nonlinear Mechanical Sensitivity in Large Deflection of Elastically-Bossed Sensor Plate under Initial Tension 848
Chun-Fu Chen
The Investigation of Modified Norris-Landzberg Acceleration Models for Reliability Assessment of Ball Grid Array Packages 852
Kuan-Jung Chung
The Effect of Cross Section Geometry of Bonding Wire on Wire Sweep for Semiconductor Packages 856
Huang-Kuang Kung
Life Prediction of High Concentration Photovoltaic Modules Subjected to Thermal Cycling Test 860
Shih-Ying Chiang
Thin Wafer Probe Breaking Strength Testing Using Microforce Tester 864
Zi-Hau Chen
Analysis of Fatigue Reliability for the Stacked Chip BGA Package by the Optimal Equivalent Solder Viewpoint 868
Hsin-En Cheng
The Investigation of Dopants on SAC Solder for Board Level Reliability 872
Chi-Ko Yu

SESSION 19: INTERCONNECTIONS & NANOTECHNOLOGY

Reliability Assessment of Stretchable Interconnect 876
Yung-Yu Hsu
Molecular Dynamics Calculations and Nanoindentation Testing of the Strain-rate and Size Dependent Material Properties of Cu_3Sn IMC 880
Ching-Feng Yu
The Challenges of Copper Wire Bonding 884
Charlie Tsung-Hsing Lu

A Fine Line/Space Fabrication Process on Flexible Polyimide Film Using Laser Direct Writing Method by Photothermal Effect of Silver Nanoparticles 888
Yi-Ting Cheng
A Novel Copper Plating Formula for Through Silicon Holes Filling in a Center-up Mode 892
Chun-wei Lu
Numerical Analysis of Moisture Diffusion in Composite Resins Containing Multiple Particles Using Hybrid Moisture Element Method 895
I-Hung Lin
3D Simulation of Fine Pitch Underfill Encapsulation 899
Chih-Chung Hsu
Thermal Measurements and Analysis of Flip-Chip LED Packages With and Without Underfills 902
Chung-Yi Tang

SESSION 20: SURFACE TREATMENT

Fabrication of Multilayer Interconnection Materials and Bonding Film for High Integration Applications 906
Myong Jae Yoo
Development of Novel Immersion Gold for Electroless Nickel and Immersion Gold Process ENIG in PCB Application 910
Kenneth Chan
IMC Investigation on Fracture Surface Between Solder Joints and Different Surface Finish Process 914
Men-Shian Li
The Investigation of the Performance of Bondability and Solderability on Various Substrate Surface Finish 918
Kuo-Yu Yeh
A Study on the Soldering Reaction between Sn3Ag0.5Cu and Electrolytic Ni Coated with A Au/Pd(P) Bilayer Surface Finish 922
Wei-Hsiang Wu
Interactions Between Sn and Cu Substrate with Various Surface Finishes 926
Wei-Han Lai

POSTER SESSION

Study PBTI and NBTI of GAA-MNC TFTs 930
Hung Ruei-Sheng
The Role of Glaze in TPH Analysis by CFD 933
Clay Hsiao
Some Special Phenomena Observed from In-line Sputtered Aluminum Doped Zinc Oxide Films 937
Shang-Chou Chang
Oxidation Properties of Sn-Cu-Ni Solders with Minor Alloying Additions 941
Bo-Chang Huang
Mechanical Properties of Electrodeposited Copper Foils for PCB Applications 945
Ding-Siang Wang
Performance of the LED Array Panel in a Confined Enclosure 949
Jin-Cherng Shyu
The Control Way of Solder Blister As Plating Machine Breakdown 953
Chen-Hung Lee
Study on Paddle Delamination for Quad Flat No Leads Package QFN 957
Chen-Hung Lee
Power Up Your Circuit Design : Material Suitable for System in Package 961
Hsien-Te Chen
Low-power Micro-spray Cooling System 965
Chun-Fu Lu
Dynamic Electrical Resistance Effects in Resistance Spot Welding 969
J. E. Ho
Study of Copper Barrel Plating Dissolution of Printed Circuit Board with Multiple Exposure Thermal Stress Testing 973
Elton Wu

Electrowetting Optical Beam Refractor 977
Hsiu-Hsiang Chen
Fabrication Technology of CMOS-MEMS Probe Chip Compatible with Electroless Nickel Plating Process 981
Kuo-Yu Lee
Design and Fabrication of Low-Insertion Loss and High-Isolation CMOS-MEMS Contact Switch for Microwave Applications 985
Yu-Kun Hsu
Low Bias Voltage and High Sensitivity CMOS Condenser Microphone Using Combined Stress Relaxation Design 988
Chin-Fu Kuo
Solid State Interfacial Reactions in SAC305/Ni-Co Couples 991
Ya-Ting Chan
Phase Equilibria Studies of the Sn-Sb-Ni System at 270°C 995
Yue-ting Chen
The Application of the Optimal Design on Twin Die Stacked Package Through the Pattern Search Method 999
Chi-huang Huang
Metal-to-metal Bonding Technology for MEMS Application 1003
Shiufang Yen
Warpage Simulation for Encapsulated Package During Post-mold Curing Process 1004
Tz-Cheng Chiu
Application of Ultraviolet UV Laser in HDI Micro Blind Via 1008
Fa-Ming Long
Reliability and Failure Analysis of Capacitive Substrate 1011
Yun-Tien Chen
The Study of Fixing Field Curvature by Flexible Image Sensor Array 1015
Chih-Ming Kuo
Electrical Current Induced Local Thermal Stress Caused on Stacked 3D-ICs 1019
Heueh-Hsien Hsu
MLP/BP-based Soft DFEs with Bit-Interleaved TCM for Distorted 16-QAM Signal Recovery in Severe ISI Channels 1021
Terng-Ren Hsu
Study on Internal Water Vapor Content and Related Military Standards of Hermetic Package Devices 1025
Shaohua Yu
Coupled Fuzzy Controller for Level Control of a Pump-Controlled Folding Machine 1029
Ray-Hwa Wong
The EMI Suppression of Ultra Thin MEMS Microphone Package 1033
Chih-Hsiang Ko
An Alternate of MPS and SPS Collocated with Dimensionally Stable Anode (DSA) for Cu Fill of Microvia and TSV 1036
Yong-Da Chiu
Electroplating Apparatus and Method Considerations for High Aspect-Ratio Through-Hole Copper Electroplating Process 1039
Ming-Yao Yen
Electroplating of Sn-2.5Ag Solders as 20 µm Pitch Micro-bumps 1042
Kuan-Chieh Huang
Photovoltaic Modules of Crystalline Solar Cells Using a New Type Assembly Structure 1046
Hsin-Hsin Hsieh
The Improvement of Delaminating at Interface Between Molding Compound And Gold Substrate Bond Pad In BGA(Ball Grid Array) Package 1050
Ming-Chang Shih
The Temperature Distribution and the Thermal Behavior in Ultra Fine Pitch Micro SnAg Solder Bump under Current Stressing 1053
Yuan-wei Chang
Influence of Trace Geometry on the Current Crowding Effect in Ultra-Fine Pitch Micro-Bump 1057
Yuan-wei Chang
Parameter Study to the interposer on the Stress Analysis of Fine Pitch 3-D Stack Package 1061
Ching-I Chen
Microstructure Evolution in Microbumps in 3D IC Packaging 1065
Ruo-wei Yang

Fast DNA Hybridization Chip Using Denature and Motion of Nucleic Acids ... 1069
Yung-Chiang Chung

Comparison of Dk/Df Variation in Different Phosphorus-containing and Bromide -containing Laminate during Moisture Absorption ... 1073
Chun-Chieh Huang

Wafer Level Glass Frit Bonding for MEMS Hermetic Packaging ... 1077
Jin-Sheng Chang

Sn-Co-(Cu) / Ni Solid/solid Interfacial Reactions ... 1081
Chih-ming Chen

Reflow Behavior of Mo Nanoparticle Added Sn-3.8Ag-0.7 Cu Solder ... 1085
Md. Arafat Mahmood

Interfacial reaction at 250°C in the Sn/Ni-7wt.%V Couple ... 1086
Kai-wen Pan

The Relationship of Life Prediction between Cyclic Bending and Thermal Cycling Testing on CSP Package Tina ... 1090
Ting-Yi Shao

3D Stacking DRAM using TSV Technology and Microbump Interconnect ... 1094
Kee-Wei Chung

Galvanostatic Electrodeposition of $SnCu_{2\text{-}4}Ni_{1\text{-}2}$ as a Lead-free Solder ... 1098
Jing-Yu Chen

Flexible Printed Circuit Board FPC Antennas for Mobile Phone Operation ... 1102
Kuo-Liang Wu

Thermal Conductivity and Morphology of Non-covalent Functionalized Graphene/epoxy Nanocomposites ... 1106
Chih-Chun Teng

Differential-and Common-Mode Characterization of Coupled Interconnect Transmission Lines Using Four-Port S-parameter Measurements ... 1110
Chien-Chang Huang

A Refined Finite Element Model Verification for IC Packaged PCB with Thermal Effects ... 1114
Bor-Tsuen Wang

Effect of Low Temperature on the Micro-impact Fracture Behavior of Sn-Ag-Cu Solder Joint ... 1118
Chang-Lin Hsu

FOMs Extraction for Quantum-Well Lasers and Low-Noise Amplifiers ... 1121
J. K. Li

Genetic Optimization of Multi-Finger High-Power Amplifiers ... 1123
T. W. Chen

Manufacturing of Complex Bi-porous Wick and Applying to a Loop Heat Pipe ... 1125
Shen-Chun Wu

Study of High Dielectric Constant Capacitors on Flexible Substrates ... 1129
Yu-Jung Huang

Structure and Method of Forming Pillar Bumps with Controllable ... 1133
Hou-Jun Hsu

Numerical Study on Thermal Management of High Power LED Die Bonding Technology ... 1138
Ming-Tsung Hung

Characteristic Analysis of Multi-layer Piezoelectric Substrate for SAW Filters by Effective Surface Permittivity Method ... 1139
Shao-Wei Luo

Development of an On-line Detecting Capillary Coating System and its Application in Silver Conductive Circuit Patterning ... 1143
Po-Ting Pan

Assessing the Impact of Uncertainty in Physics of Failure Analysis of BGA Solder Joints Fatigue Damage ... 1147
Mei-Ling Wu

Mechanical Analysis and Design of Ultra-Thin-Chip-on-Flex (UTCOF) with Anisotropic Conductive Adhesive (ACA) Joints ... 1151
Hsien-Chie Cheng

Author Index